

## PATENT ASSIGNMENT COVER SHEET

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|---|----------------------------------|
| <b>SUBMISSION TYPE:</b>   | NEW ASSIGNMENT                   |
| <b>NATURE OF CONVEYANCE:</b>  | ASSIGNMENT                       |
| <b>CONVEYING PARTY DATA</b>   |                                  |
| <b>Name</b>   | <b>Execution Date</b>            |
| YING HUANG  | 06/05/2014                       |
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| <b>City:</b>  | Shenzhen, Guangdong              |
| <b>State/Country:</b>   | CHINA                            |
| <b>Postal Code:</b>   | 518129                           |
| <b>PROPERTY NUMBERS Total: 1</b>  |                                  |
| <b>Property Type</b>  | <b>Number</b>                    |
| Application Number:   | 14661905                         |
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| <b>ATTORNEY DOCKET NUMBER:</b>  | HW720099                         |
| <b>NAME OF SUBMITTER:</b>   | JOHN B. CONKLIN                  |
| <b>SIGNATURE:</b>   | /John B. Conklin/                |
| <b>DATE SIGNED:</b>   | 03/20/2015                       |
| <b>Total Attachments: 2</b>   |                                  |
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| source=Assignment#page2.tif   |                                  |

**ASSIGNMENT**

**WHEREAS, I,**

Ying HUANG  
Huawei Administration Building,  
Bantian, Longgang District,  
Shenzhen, 518129, Guangdong,  
P.R. China

have invented and own a certain invention entitled:  
**METHOD AND ENODEB FOR FORWARDING DOWNLINK AND UPLINK PACKETS  
BASED ON S1 HANDOVER**

for which invention I have executed an application (provisional or non-provisional) for a U.S. patent, which was filed on 03/18/2015, under U.S. Application No. 14/661,905, and

**WHEREAS, HUAWEI TECHNOLOGIES CO., LTD.**, of Huawei Administration Building, Bantian, Longgang District, Shenzhen, 518129, Guangdong, P.R. China, hereinafter referred to as Assignee, is desirous of acquiring the entire domestic and foreign right, title, and interest in and under the invention described in the patent application.

**NOW, THEREFORE**, for good and valuable considerations, the receipt and sufficiency of which are hereby acknowledged, I assign and transfer to the Assignee and the Assignee's legal representatives, successors and assigns the full and exclusive rights in and to the invention in the U.S. and every foreign country and the entire right, title, and interest in and to the patent application and other such applications (e.g., provisional applications, non-provisional applications, continuations, continuations-in-part, divisionals, reissues, reexaminations, National phase applications, including petty patent applications, and utility model applications) that may be filed in the United States and every foreign country on the invention, and the patents, extensions, or derivations thereof, both foreign and domestic, that may issue thereon, and I do hereby authorize and request the Commissioner of Patents to issue U.S. patents to the above-mentioned Assignee agreeably with the terms of this assignment document.

**I HEREBY AUTHORIZE** the Assignee to insert in this assignment document the filing date and application number of the application if the date and number are unavailable at the time this document is executed.

**I DO HEREBY COVENANT** and agree with the Assignee that I will not execute any writing or do any act whatsoever conflicting with the terms of this assignment document set forth herein, and that I will at any time upon request, without further or additional consideration, but at the expense of the Assignee, execute such additional assignments and other writings and do such additional acts as the Assignee may deem necessary or desirable to perfect the Assignee's enjoyment of this assignment, and render all necessary assistance in making application for and obtaining original, continuation, continuation-in-part, divisional, reissued, reexamined, and National phase patents of the U.S. or of any and all foreign countries on the invention, and in enforcing any rights or chooses in action accruing as a result of such applications or patents, and by executing statements and other affidavits, it being understood

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In re Appln. of HUANG.  
Attorney Docket No. HW720099

that the foregoing covenant and agreement shall bind, and inure to the benefit of, the assigns and legal representatives of all parties hereto.

IN WITNESS WHEREOF, I have hereunder set my hand on the dates shown below.

Date Jan 5, 2014

Ying HUANG  
Ying HUANG